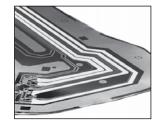
CHO-FLEX[™] 601

CONDUCTIVE COATING



Customer Value Proposition:

CHO-FLEXTM 601 one-component conductive coating is designed specifically for EMI shielding of copper/Kapton* flexible circut t laminates and for printing circuits on Kapton film. Upon cure, this coating exhibits excellent adhesive properties, a high degree of flexibility, thermal stability, high conductivity and superior peel strength. CHO-FLEX 601 coating can be applied by spraying or silk-screening methods, and can withstand wave solder temperatures above 500°F without losing any of its exceptional properties.

Features & Benefits:

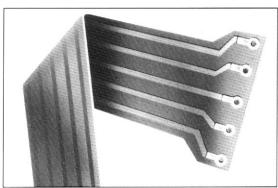
- One part silver-filled polyurethane coating.
- Spray or screen application.
- High degree of flexibility.
- Withstands wave solder temperatures in excess of 500°F (262°C).
- Exceptional pot life at room temperature. Cures only when heated, i.e >250°F (122°C)
- Cured resistivity of 100 milliohms or better after wave solder process.
- Kapton is a registered tradename of E. I. du Pont de Nemours.

Contact Information:

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Typical Applications:

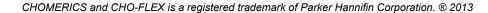
CHO-FLEX 601 coating may be silk-screened as is. If thinning is desired, the coating may be thinned with DBE (Dibasic Ester). For spray application. thin CHO-FLEX coating with a sovent blend of MEK/Butanol/Isopropal alcohol at a ratio of 15/10/6 by volume. Thin two parts of coating with one part of thinner and

mix completely (preferably in paint shaker)

Table 1 Typical Properties

| CHO-FLEX 601 | |
|--|---|
| Typical Properties** | Typical Values |
| Binder | Polyurethane |
| Filler | Silver |
| Color | Silver |
| Solids by weight | 58% |
| Specific Gravity | 1.67 |
| Surface Resistivity001" film | 0.05 ohm / square |
| Volume Resistivity001" film | 0.00015 ohm-cm |
| Specific Gravity | 1.67 |
| Adhesion per ASTM D3359-78 | 5B |
| Shelf Life at 21°C (70°F) | 6 months |
| Suggested Cure Cycle: Initial Cure Press Cure Wave Solder | 162 °C (325 °F)/4-5 minutes (dry to touch) 184 °C (360 °F)/90 minutes @400PSI (28.2 kg/cm2) 262 °C (500 °F)/3-4 seconds |

^{**} Data based on ilk screen application with 235 nesh open screen. Coating applied to pumiced Kapton. Application at 0.8 to 1.2 mils.



TB 1150 EN Reformatted April 2014 from original document 1995

